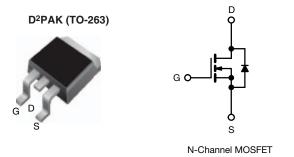
Vishay Siliconix

COMPLIANT HALOGEN

**FREE** 

# **E Series Power MOSFET**

PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max. 650				
$R_{DS(on)}$ max. ( $\Omega$ ) at 25 °C	$V_{GS} = 10 \text{ V}$	0.28		
Q <sub>g</sub> max. (nC) 78				
Q <sub>gs</sub> (nC)	9			
Q <sub>gd</sub> (nC) 17				
Configuration	Single			



#### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qq
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>q</sub>)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912"><u>www.vishav.com/doc?99912</u></a>

#### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

ORDERING INFORMATION			
Package	D <sup>2</sup> PAK (TO-263)		
Lead (Pb)-free and Halogen-free	SiHB15N60E-GE3		

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub>	= 25 °C, unl	less otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			$V_{DS}$	600	V
Gate-Source Voltage			$V_{GS}$	± 30	v
Continuous Proin Current (T = 150 °C)	V <sub>GS</sub> at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	- I <sub>D</sub> -	15	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		9.6	А
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	39	
Linear Derating Factor				1.4	W/°C
Single Pulse Avalanche Energy <sup>b</sup>			E <sub>AS</sub>	102	mJ
Maximum Power Dissipation			$P_{D}$	180	W
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Drain-Source Voltage Slope $V_{DS} = 0 \text{ V to } 80 \text{ % } V_{DS}$		dV/dt	70	V/ns	
Reverse Diode dV/dt d			7.7	V/ns	
Soldering Recommendations (Peak temperature) c for 10 s				300	°C

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $V_{DD}$  = 50 V, starting  $T_J$  = 25 °C, L = 11.6 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 4.2 A.
- c. 1.6 mm from case.
- d.  $I_{SD} \le I_D$ ,  $dI/dt = 100 \text{ A/}\mu\text{s}$ , starting  $T_J = 25 \,^{\circ}\text{C}$ .



# Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER SYMBOL TYP. MAX. UNIT					
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62	°C/W	
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	0.7	G/ VV	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		•					
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> :	= 0 V, I <sub>D</sub> = 250 μA	600	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.71	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2	-	4	V
Octo Course Leelings	I <sub>GSS</sub>	V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Gate-Source Leakage			V <sub>GS</sub> = ± 30 V			± 1	μΑ
Zara Cata Valtaga Drain Current	1	V <sub>DS</sub> =	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 \	/, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 8 A	-	0.23	0.28	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub>	= 30 V, I <sub>D</sub> = 8 A	-	4.6	-	S
Dynamic		•		•	•	•	
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 V$ ,		-	1350	-	
Output Capacitance	C <sub>oss</sub>		$V_{DS} = 100 \text{ V},$	-	70	-	1
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1 MHz		-	5	-	pF
Effective Output Capacitance, Energy Related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V		-	53	-	
Effective Output Capacitance, Time Related <sup>b</sup>	C <sub>o(tr)</sub>			-	177	-	
Total Gate Charge	Q <sub>g</sub>			-	39	78	1
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	V <sub>GS</sub> = 10 V I <sub>D</sub> = 8 A, V <sub>DS</sub> = 480 V		11	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	1			17	-	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 480 V, I <sub>D</sub> = 8 A,		-	16	32	
Rise Time	t <sub>r</sub>			-	26	52	
Turn-Off Delay Time	t <sub>d(off)</sub>		= 10 V, $R_q = 9.1 \Omega$	-	41	82	ns
Fall Time	t <sub>f</sub>			-	22	44	
Gate Input Resistance	R <sub>g</sub>	f = 1 MHz, open drain		0.3	0.86	1.7	Ω
<b>Drain-Source Body Diode Characteristic</b>	S						
Continuous Source-Drain Diode Current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	15	
Pulsed Diode Forward Current	I <sub>SM</sub>			-	-	60	A
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 8 A, V <sub>GS</sub> = 0 V		-	1.0	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> = 8 A, dl/dt = 100 A/ $\mu$ s, V <sub>R</sub> = 25 V		-	302	604	ns
Reverse Recovery Charge	Q <sub>rr</sub>			-	4.0	8	μC
Reverse Recovery Current	I <sub>RRM</sub>			_	24	_	A

#### Notes

a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .

b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

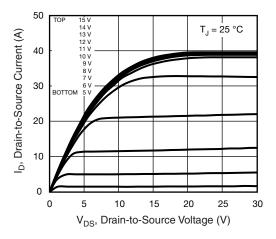


Fig. 1 - Typical Output Characteristics

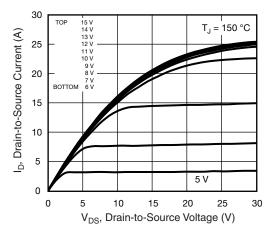


Fig. 2 - Typical Output Characteristics

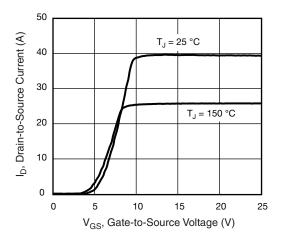


Fig. 3 - Typical Transfer Characteristics

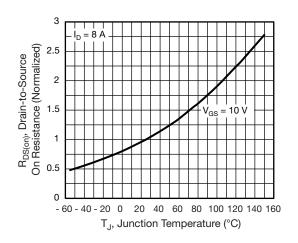


Fig. 4 - Normalized On-Resistance vs. Temperature

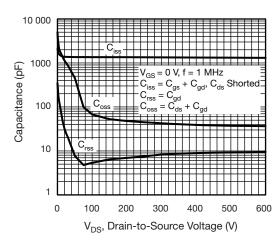


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

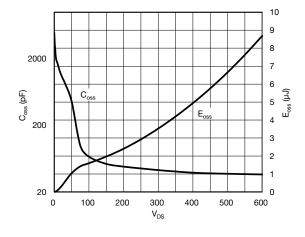


Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$ 



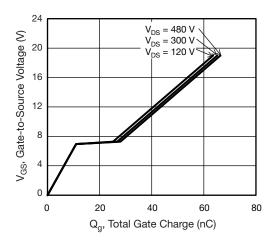


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

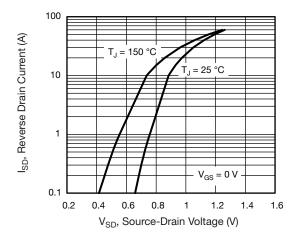


Fig. 8 - Typical Source-Drain Diode Forward Voltage

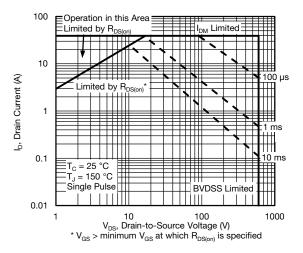


Fig. 9 - Maximum Safe Operating Area

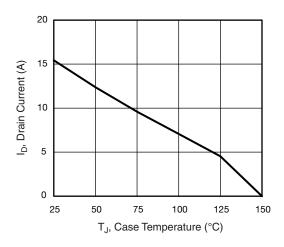


Fig. 10 - Maximum Drain Current vs. Case Temperature

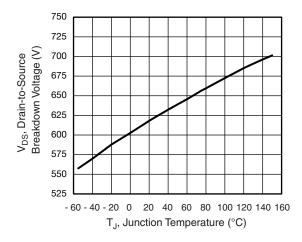


Fig. 11 - Temperature vs. Drain-to-Source Voltage



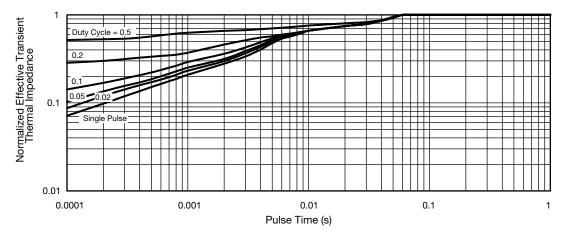


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

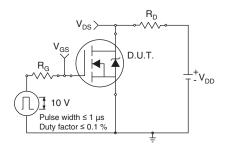


Fig. 13 - Switching Time Test Circuit

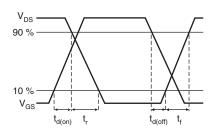


Fig. 14 - Switching Time Waveforms

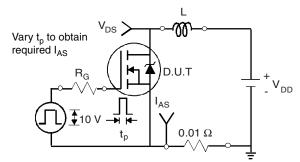


Fig. 15 - Unclamped Inductive Test Circuit

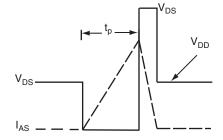


Fig. 16 - Unclamped Inductive Waveforms

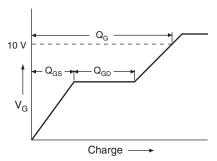


Fig. 17 - Basic Gate Charge Waveform

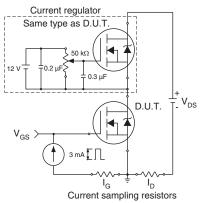
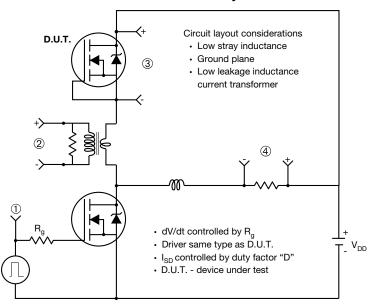


Fig. 18 - Gate Charge Test Circuit



### Peak Diode Recovery dV/dt Test Circuit



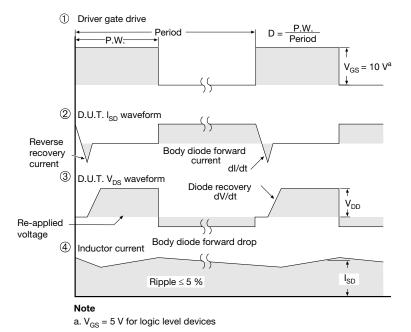


Fig. 19 - For N-Channel

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## **TO-263AB (HIGH VOLTAGE)**







	MILLIN	METERS	INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
С	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380

	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
D1	6.86	-	0.270	-
Е	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	ı
е	2.54 BSC		0.100 BSC	
Н	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.65	ı	0.066
L2	-	1.78	-	0.070
L3	0.25 BSC		0.010	BSC
L4	4.78	5.28	0.188	0.208

ECN: S-82110-Rev. A, 15-Sep-08

DWG: 5970

#### Notes

- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Dimensions are shown in millimeters (inches).
- 3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
- 4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
- 5. Dimension b1 and c1 apply to base metal only.
- 6. Datum A and B to be determined at datum plane H.
- 7. Outline conforms to JEDEC outline to TO-263AB.

Document Number: 91364 www.vishay.com Revision: 15-Sep-08





## RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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